

### **III. REMARKS**

1. Claims 1-10 remain in the application. Claims 1 and 7 have been amended.

2. Applicants wish to express their appreciation for the courtesies extended by the Examiner during the telephone conversation of 4 August 2005.

3. Applicants wish to express their appreciation for the indication that claims 7-10 would be allowable if rewritten in independent form including all the limitations of the base claim and any intervening claims. However, Applicants believe that claims 7-10 are patentable as they stand for the reasons given below.

4. Applicants respectfully submit that claims 1-6 are not anticipated by Hamano (US 6,366,463).

Hamano fails to disclose or suggest a heat sink arrangement having a support means with alignment means for engaging the equipment module and a pivotable heat sink, as recited by claim 1. There is nothing in Hamano related to a support means with alignment means for engaging an equipment module. Hamano's heat sink operates as a cover and does not have an alignment means that engages an equipment module.

Furthermore, Hamano's heat sink is not pivoted by the action of inserting the equipment module into the support means, as recited by claim 1. Hamano's heat sink 21 is fastened by screws 30 to printed circuit board 15. The heat sink is also fastened to a heat pipe 22, which in turn is fastened to the equipment frame. The heat sink 21 may be rotated away to exchange CPU 16

by unfastening screws 30, however, the heat sink does not pivot by the action of inserting an equipment module into a support means. There is no support means as part of the heatsink assembly, and the action of inserting the CPU does not cause the heat sink to pivot. Instead, the heatsink must be manually rotated out of the way as a separate operation to install the CPU. After the CPU 16 is installed, the heatsink must be manually rotated downward to make contact with the CPU. Insertion of the CPU does not cause the heat sink to pivot.

At least for these reasons, Applicants submit that Hamano fails to anticipate independent claim 1 and dependent claims 2-10.

5. Claims 1-3, 5, and 6 are not anticipated by Yan et al. (US 6,447,322, "Yan") under 35 USC 102(a).

Yan, like Hamano, fails to disclose or suggest a heat sink arrangement having a support means with alignment means for engaging the equipment module and a pivotable heat sink. In addition, the heat sinks of the test socket in Yan are not pivoted by the action of inserting the equipment module into the support means. The heat sinks 20 are moved to a loading position and the integrated circuit 12 is loaded. Once the integrated circuit is loaded into the assembly, the heat sinks 20 are released and make contact with the integrated circuit 12. The action of inserting the integrated circuit does not cause the heat sinks to pivot.

Both Hamano and Yan require the CPU or integrated circuit to be inserted into its holder and then, in a separate step, the heat sinks to be moved into place to make contact with the CPU or integrated circuit. This is in contrast to the present invention as recited by claim 1 whereby it is the action of

inserting the equipment module into the support means that causes the heat sink to be pivoted in such a way that a surface of the heat sink is brought into contact with a surface of the equipment module.

At least for these reasons, Applicants respectfully submit that Yan fails to anticipate independent claim 1 and dependent claims 2, 3, 5, and 6.

6. Claim 4 is patentable over the combination of Yan in view of Garner et al. (US 5,822,187, "Garner") under 35 USC 103(a).


Garner fails to supply the features of claim 1 missing from Yan, that is, a support means with alignment means for engaging an equipment module, and the heat sink being pivoted by the action of inserting the equipment module into the support means. Therefore, claim 4 is patentable over the combination of Yan and Garner.

For all of the foregoing reasons, it is respectfully submitted that all of the claims now present in the application are clearly novel and patentable over the prior art of record, and are in proper form for allowance. Accordingly, favorable reconsideration and allowance is respectfully requested. Should any unresolved issues remain, the Examiner is invited to call Applicants' attorney at the telephone number indicated below.

A check in the amount of \$910.00 is enclosed for a one (1) month extension of time (\$120.00) and for the RCE fee (\$790.00).

The Commissioner is hereby authorized to charge payment for any fees associated with this communication or credit any over payment to Deposit Account No. 16-1350.

Respectfully submitted,

  
Joseph V. Gamberdell, Jr.  
Reg. No. 44,695

14 October 2005  
Date


Perman & Green, LLP  
425 Post Road  
Fairfield, CT 06824  
(203) 259-1800  
Customer No.: 2512

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